

N- and P-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY				
	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
N-Channel	40	0.016 at V _{GS} = 10 V	8	56
		0.019 at V _{GS} = 4.5 V	8	
P-Channel	- 40	0.025 at V _{GS} = - 10 V	- 8	6
		0.032 at V _{GS} = - 4.5 V	- 7.5	

FEATURES

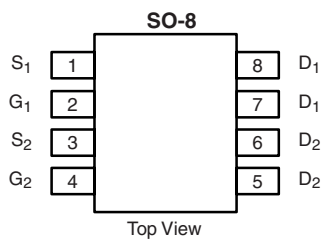
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- 100 % R_g Tested



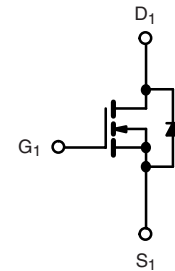
RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

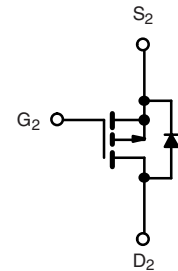
- CCFL Inverter



Ordering Information: Si4563DY-T1-E3 (Lead (Pb)-free)
Si4563DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V _{DS}	40	- 40	V
Gate-Source Voltage		V _{GS}	± 16		
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I _D	8	- 8	A
	T _C = 70 °C		8	- 6.5	
	T _A = 25 °C		8 ^{b, c}	- 6.6 ^{b, c}	
	T _A = 70 °C		6.5 ^{b, c}	- 5.2 ^{b, c}	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	20	- 20	
Source-Drain Current Diode Current	T _C = 25 °C	I _S	2.7	- 2.7	
	T _A = 25 °C		1.6 ^{b, c}	- 1.6 ^{b, c}	
Pulsed Source-Drain Current		I _{SM}	20	- 20	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20	25	
Single Pulse Avalanche Energy		E _{AS}	20	31.2	
Maximum Power Dissipation	T _C = 25 °C	P _D	3.25	3.25	W
	T _C = 70 °C		2.10	2.10	
	T _A = 25 °C		2.0 ^{b, c}	2.0 ^{b, c}	
	T _A = 70 °C		1.25 ^{b, c}	1.25 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	N-Channel		P-Channel		Unit
			Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	45	62.5	45	62.5	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	29	38	29	38	

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 120 °C/W.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit	
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	N-Ch	40			V	
		V _{GS} = 0 V, I _D = - 250 μA	P-Ch	- 40				
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA	N-Ch		40		mV/°C	
		I _D = - 250 μA	P-Ch		- 40			
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	N-Ch		- 4.8			
		I _D = - 250 μA	P-Ch		4.0			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	0.8		2.0	V	
		V _{DS} = V _{GS} , I _D = - 250 μA	P-Ch	- 0.8		- 2.2		
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 16 V	N-Ch			100	nA	
			P-Ch			- 100		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	N-Ch			1	μA	
		V _{DS} = - 40 V, V _{GS} = 0 V	P-Ch			- 1		
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	N-Ch			10		
		V _{DS} = - 40 V, V _{GS} = 0 V, T _J = 55 °C	P-Ch			- 10		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	N-Ch	20			A	
		V _{DS} = - 5 V, V _{GS} = - 10 V	P-Ch	- 20				
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A	N-Ch		0.013	0.016	Ω	
		V _{GS} = - 10 V, I _D = - 5 A	P-Ch		0.020	0.025		
		V _{GS} = 4.5 V, I _D = 4 A	N-Ch		0.015	0.019		
		V _{GS} = - 4.5 V, I _D = - 4 A	P-Ch		0.025	0.032		
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 5 A	N-Ch		23		S	
		V _{DS} = - 15 V, I _D = - 5 A	P-Ch		18			
Dynamic ^a								
Input Capacitance	C _{iss}	N-Channel V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz	N-Ch		2390		pF	
			P-Ch		2120			
Output Capacitance	C _{oss}		P-Channel V _{DS} = - 20 V, V _{GS} = 0 V, f = 1 MHz	N-Ch		270		
				P-Ch		310		
Reverse Transfer Capacitance	C _{rss}		N-Ch		165			
			P-Ch		235			
Total Gate Charge	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 5 A	N-Ch		56	85	nC	
		V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 5 A	P-Ch		52	80		
		N-Channel V _{DS} = 20 V, V _{GS} = 4.5 V I _D = 5 A	N-Ch		26	40		
			P-Ch		25.5	39		
Gate-Source Charge	Q _{gs}	P-Channel V _{DS} = - 20 V, V _{GS} = - 4.5 V, I _D = - 5 A	N-Ch		5.5			
			P-Ch		5.1			
Gate-Drain Charge	Q _{gd}		N-Ch		9.7			
			P-Ch		11.7			
Gate Resistance	R _g	f = 1 MHz	N-Ch		2.6	4.0	Ω	
			P-Ch		5.8	9.0		



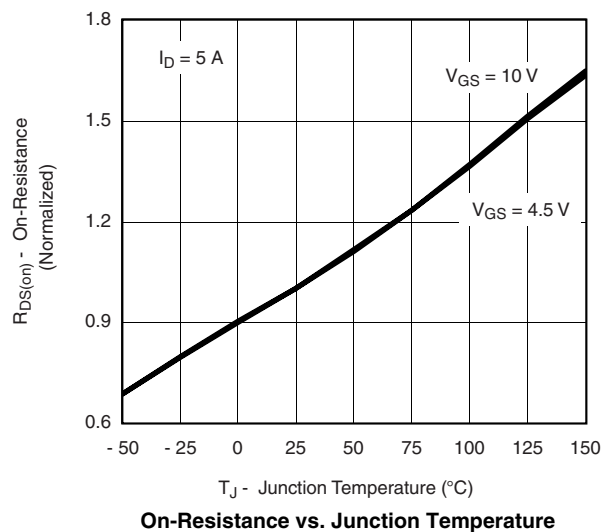
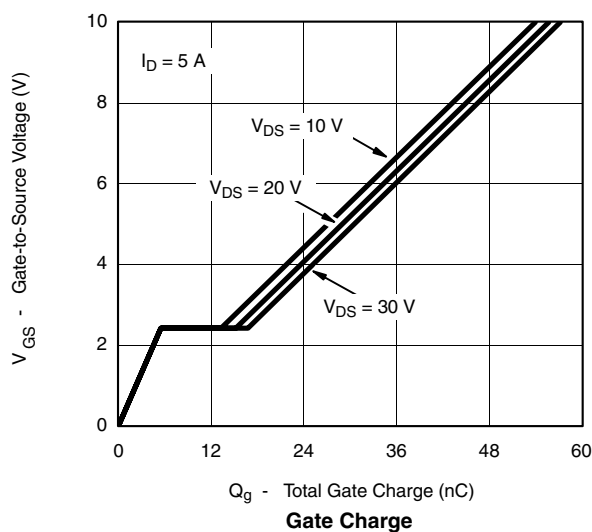
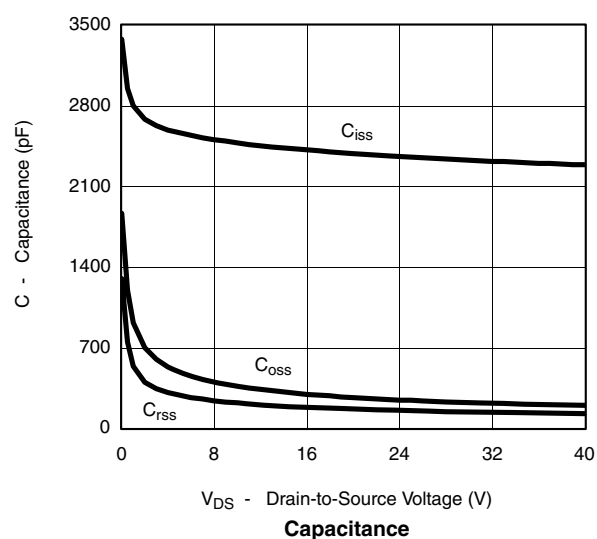
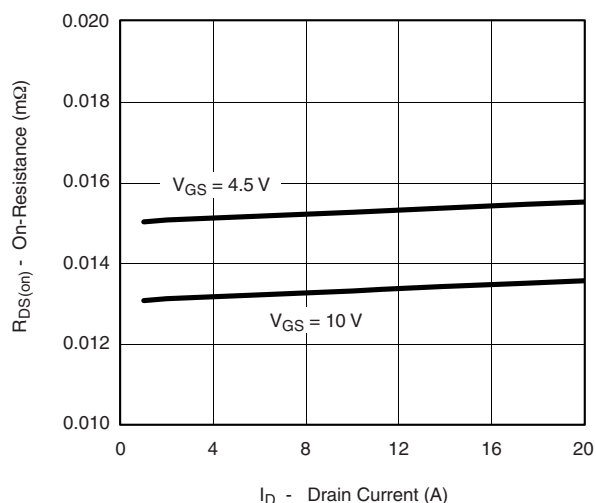
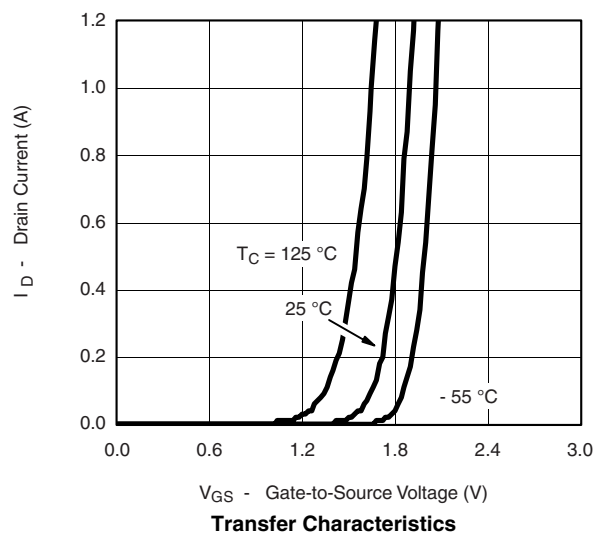
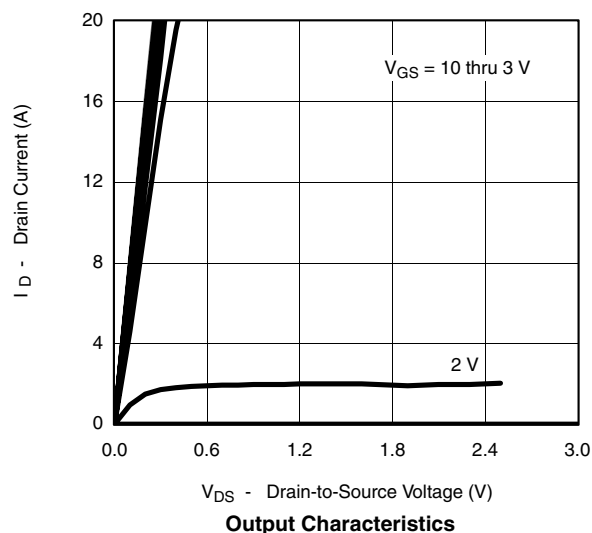
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit
Dynamic ^a							
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 20 V, R _L = 4 Ω I _D ≅ 5 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch		15	23	ns
			P-Ch		13	20	
Rise Time	t _r		N-Ch		20	30	
			P-Ch		16	25	
Turn-Off Delay Time	t _{d(off)}	P-Channel V _{DD} = - 20 V, R _L = 4 Ω I _D ≅ - 5 A, V _{GEN} = - 10 V, R _g = 1 Ω	N-Ch		56	85	
			P-Ch		75	115	
Fall Time	t _f		N-Ch		10	15	
			P-Ch		68	105	
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 20 V, R _L = 4 Ω I _D ≅ 5 A, V _{GEN} = 4.5 V, R _g = 1 Ω	N-Ch		88	135	
			P-Ch		33	50	
Rise Time	t _r		N-Ch		117	180	
			P-Ch		93	140	
Turn-Off Delay Time	t _{d(off)}	P-Channel V _{DD} = - 20 V, R _L = 4 Ω I _D ≅ - 5 A, V _{GEN} = - 4.5 V, R _g = 16 Ω	N-Ch		62	95	
			P-Ch		80	120	
Fall Time	t _f		N-Ch		19	30	
			P-Ch		69	105	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	N-Ch			2.7	A
			P-Ch			- 2.7	
Pulse Diode Forward Current ^a	I _{SM}		N-Ch			20	
			P-Ch			- 20	
Body Diode Voltage	V _{SD}	I _S = 1.5 A	N-Ch		0.69	1.2	V
		I _S = - 1.6 A	P-Ch		- 0.72	- 1.2	
Body Diode Reverse Recovery Time	t _{rr}	N-Channel I _F = 2 A, dI/dt = 100 A/μs, T _J = 25 °C	N-Ch		62	95	ns
			P-Ch		49	75	
Body Diode Reverse Recovery Charge	Q _{rr}		N-Ch		62	95	nC
			P-Ch		42	65	
Reverse Recovery Fall Time	t _a	P-Channel I _F = - 2 A, dI/dt = - 100 A/μs, T _J = 25 °C	N-Ch		26		ns
			P-Ch		19		
Reverse Recovery Rise Time	t _b		N-Ch		36		
			P-Ch		30		

Notes:

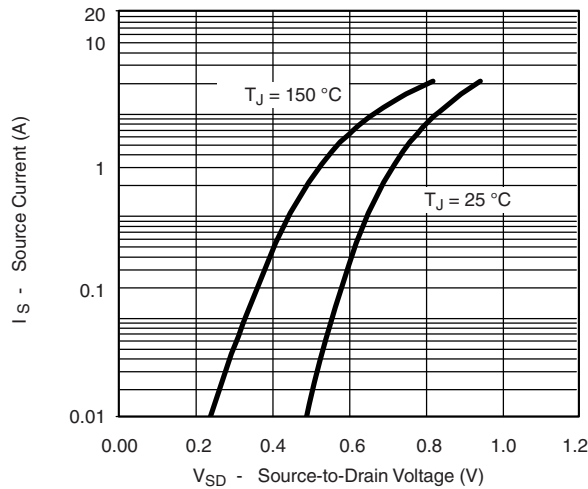
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\text{ }\%$.

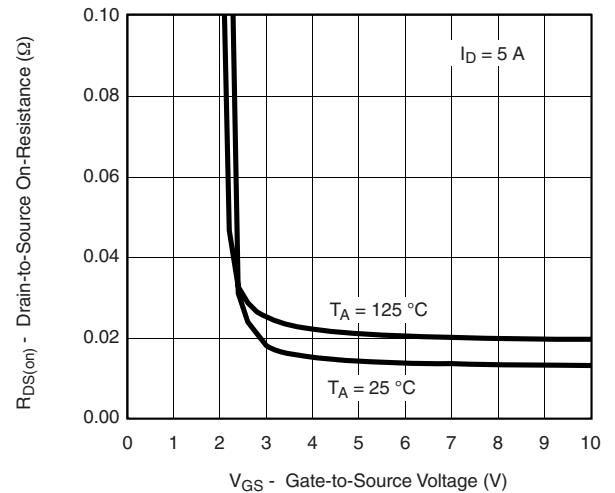
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

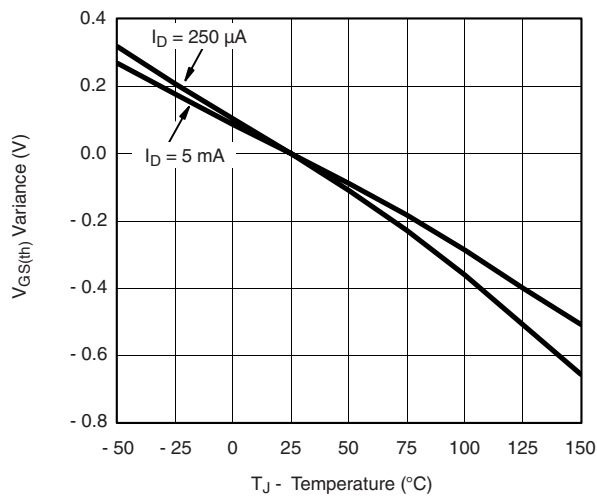
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



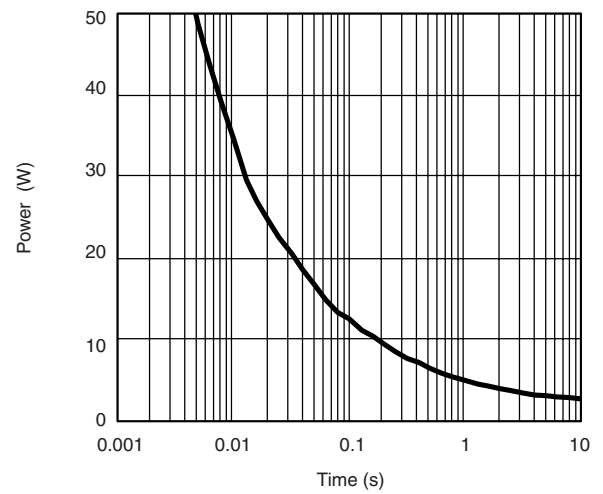
Source-Drain Diode Forward Voltage



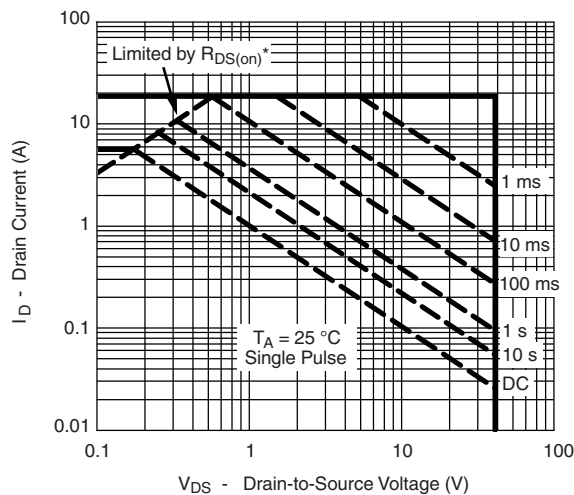
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

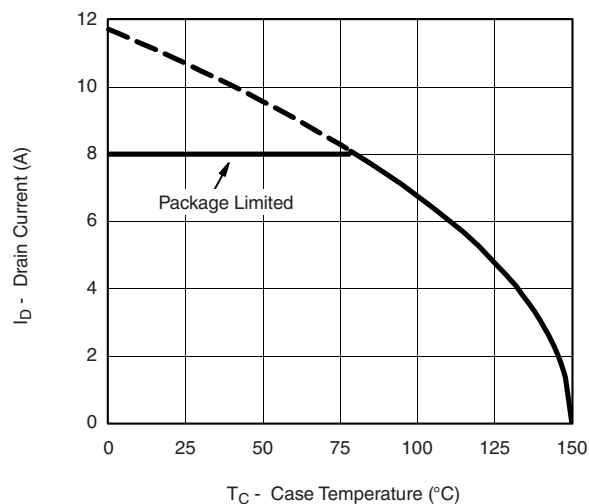
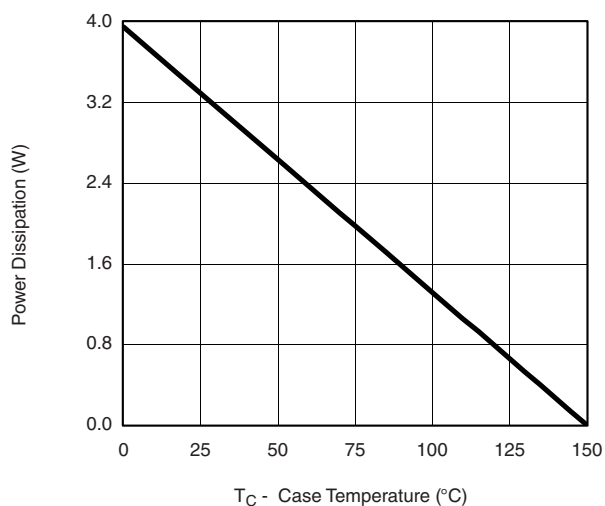
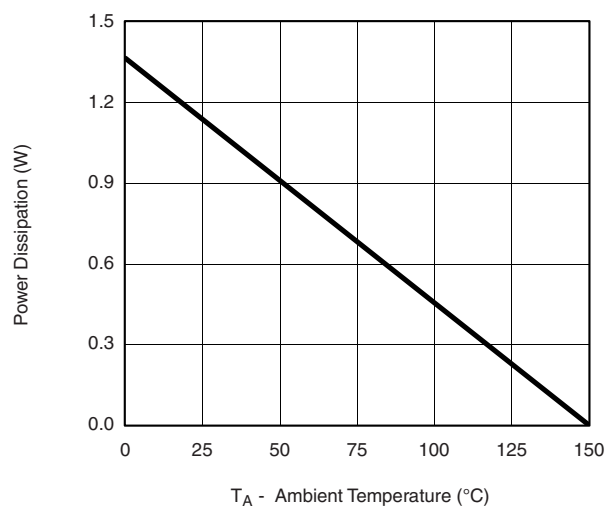


Single Pulse Power, Junction-to-Ambient



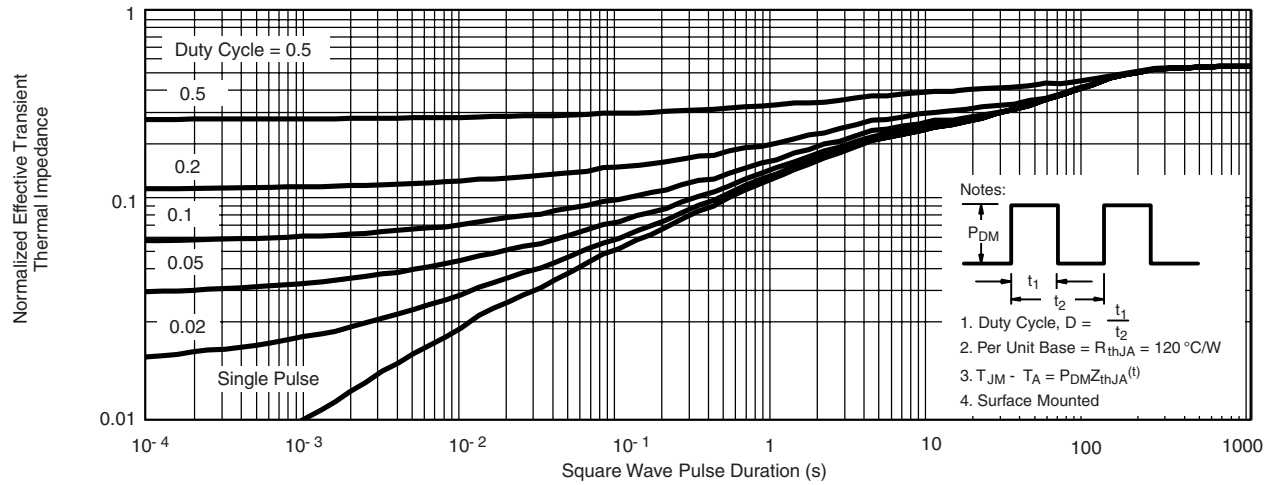
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

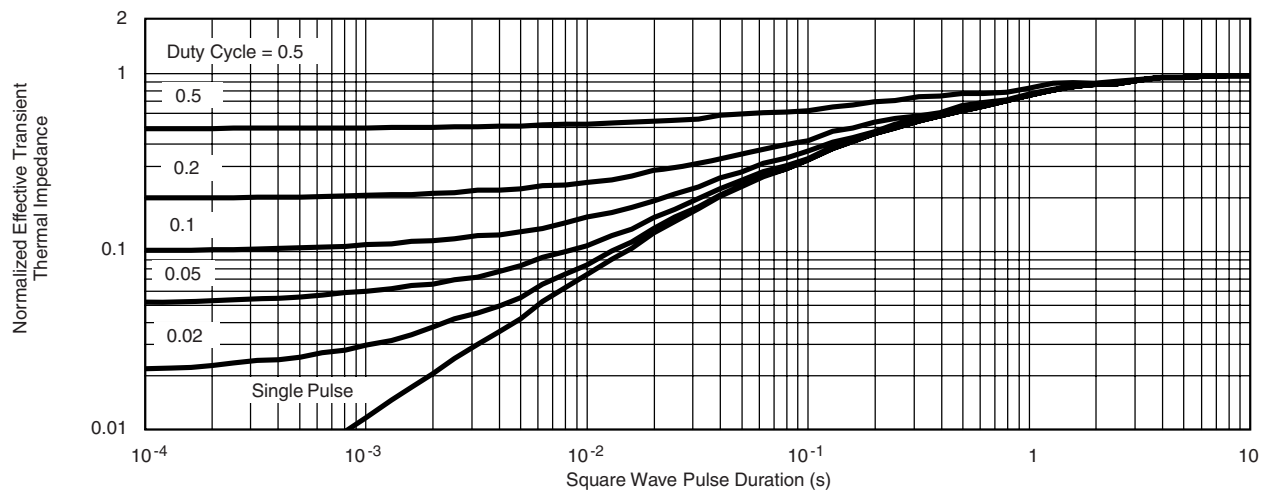
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Current Derating*****Power Derating, Junction-to-Foot****Power Derating, Junction-to-Ambient**

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

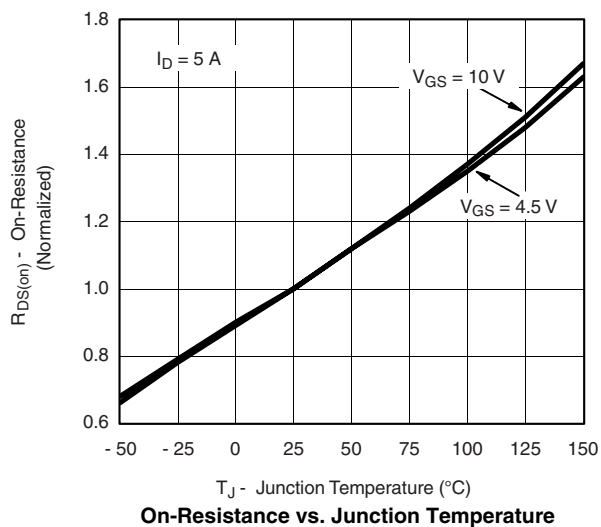
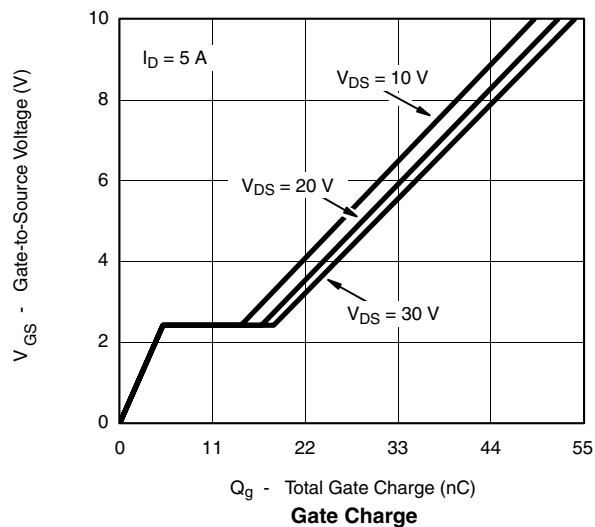
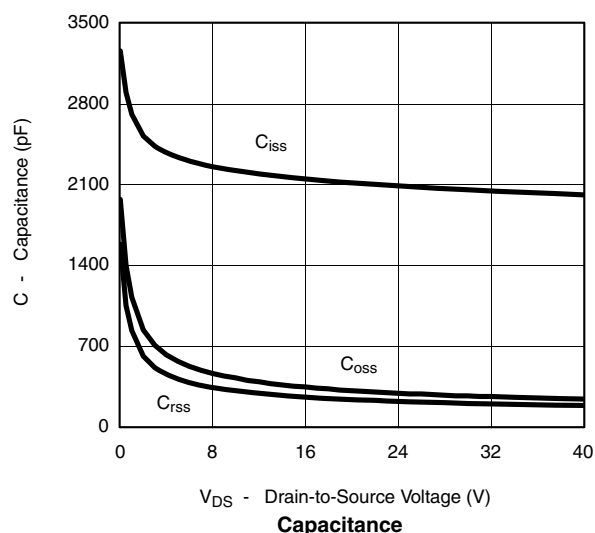
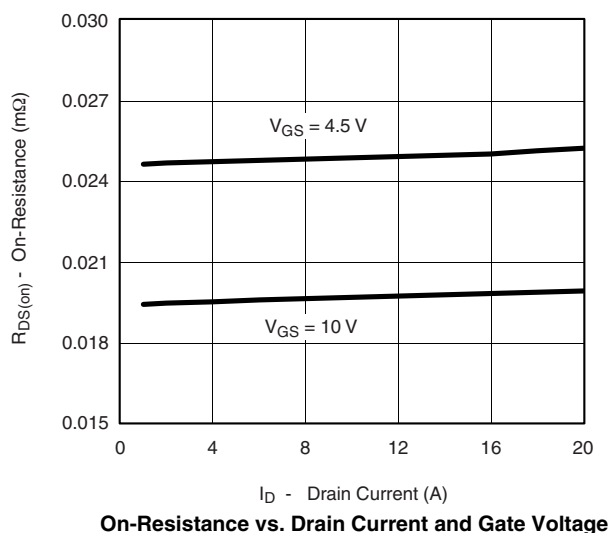
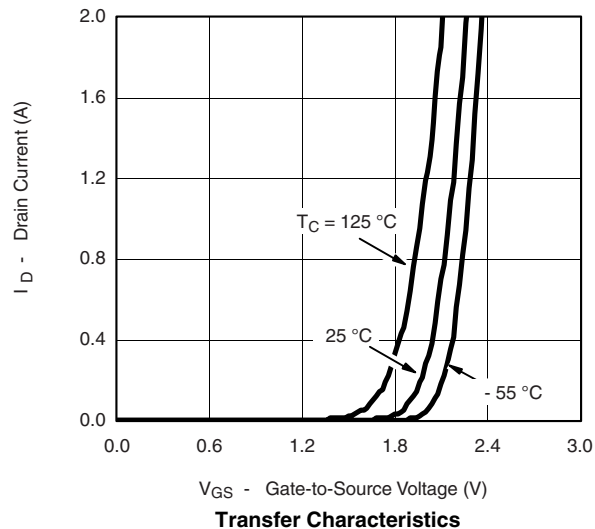
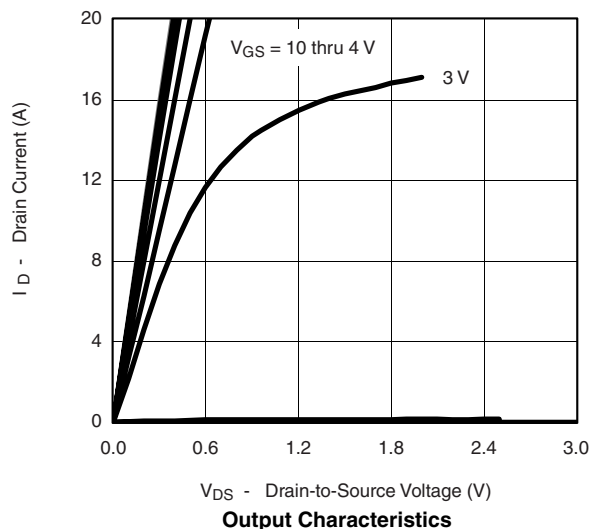
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



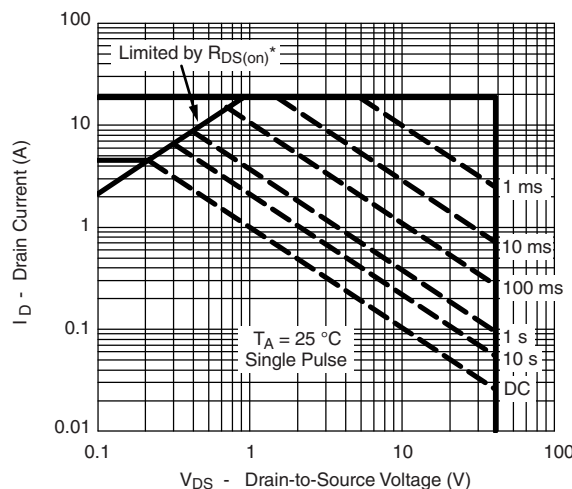
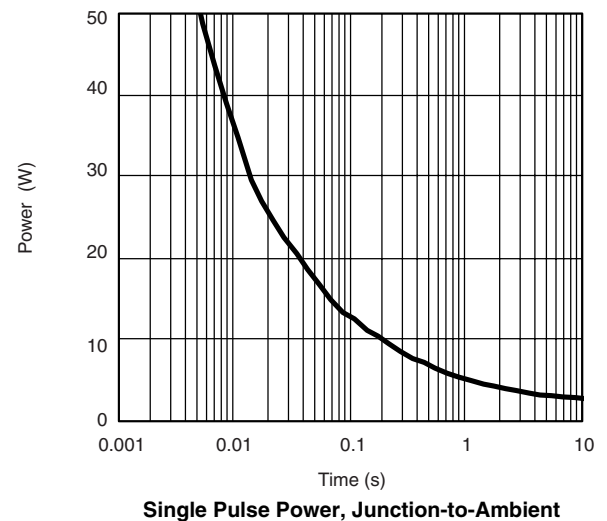
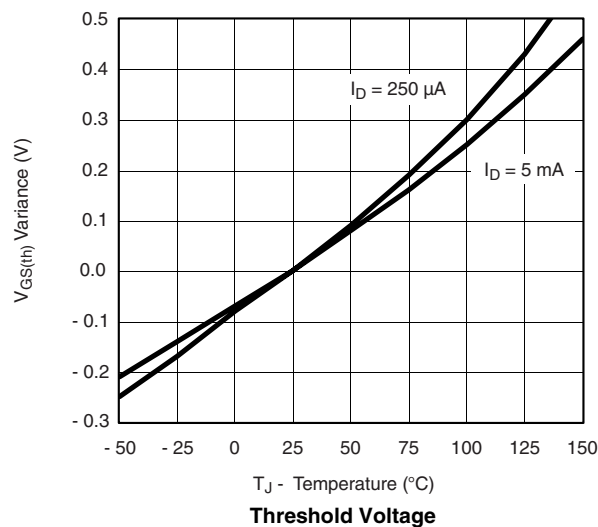
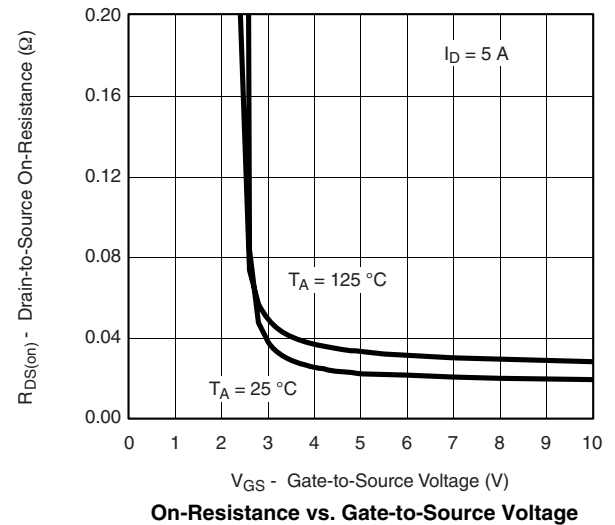
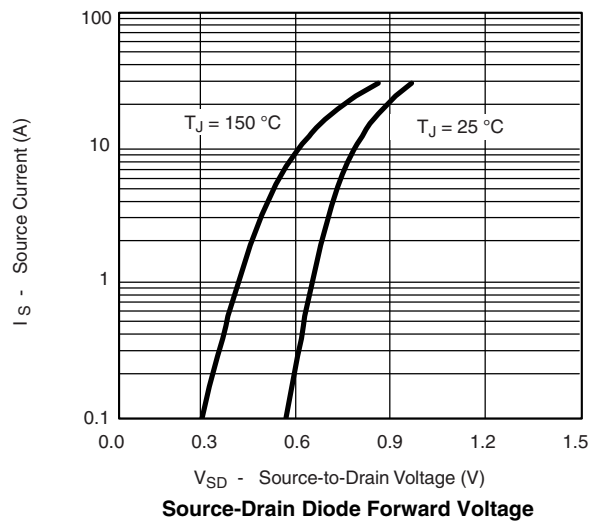
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

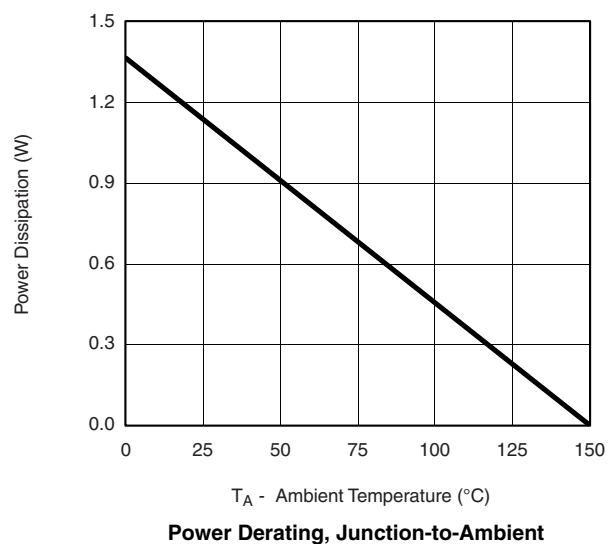
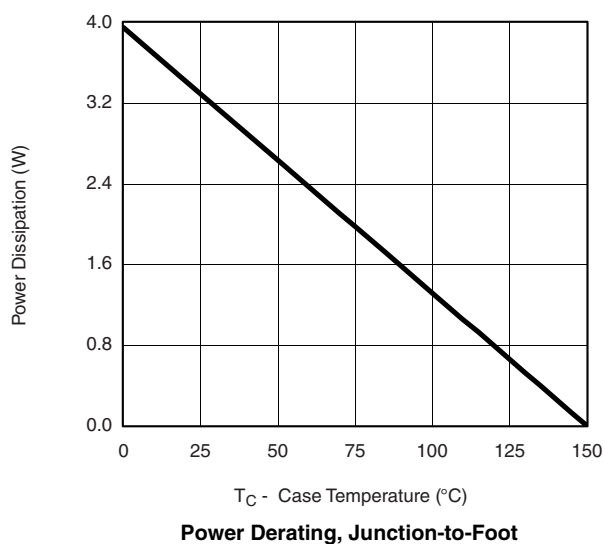
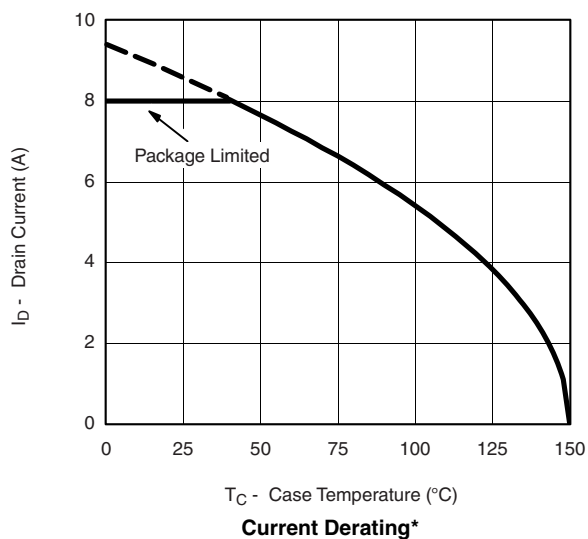
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



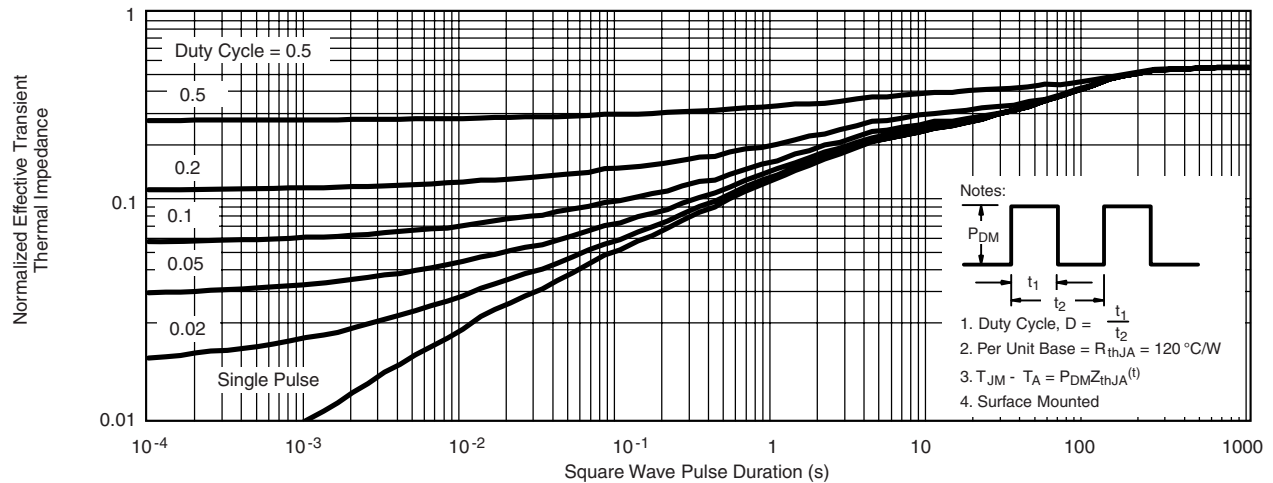
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

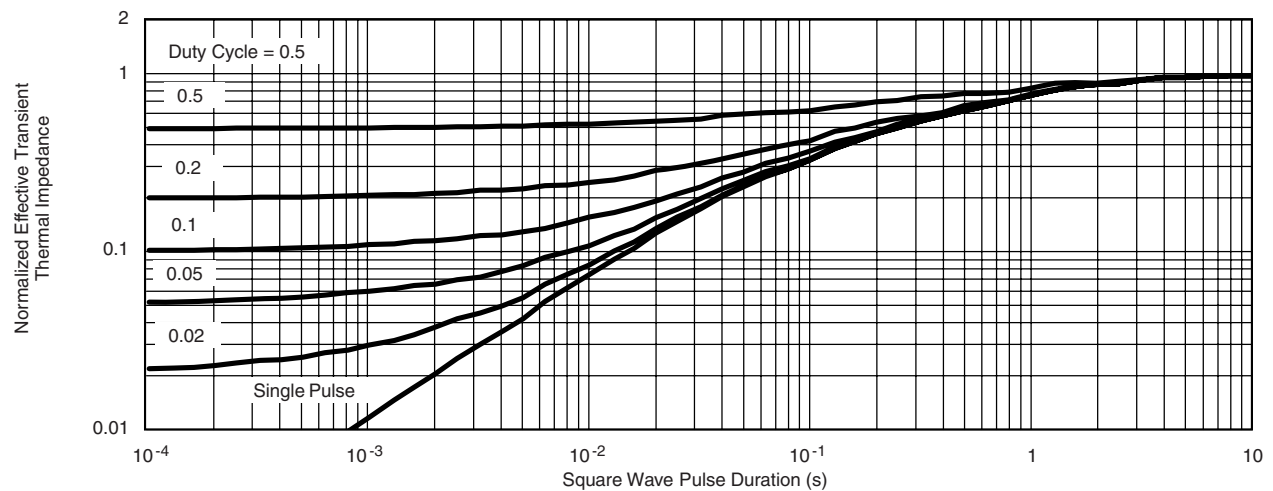
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg73513.



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.